

MYPro series MY700™ Jet Printer and Dispenser

Specifications
March 2022



Specifications MYPro series **MY700™**

MACHINE PLATFORM	
Jet frequency	720,000DPH/1,080,000DPH ⁽¹⁾
Gantry type	X /Y linear motor
Servo	Advanced DSP motion control
Gantry acceleration, max	3g (30m/s ²)
Active field of view	16x16 mm

(1) Requires optional high-speed option.

PRODUCTION PERFORMANCE	
Single dot repeatability, 3σ (X,Y) ⁽²⁾	± 35μm
Single dot accuracy, Cpk=1.0 (X,Y) ⁽²⁾	± 40μm

(2) Single applicator solder paste, 722dot pattern, 3mm pitch.

CAPABILITY	MY700JX	
	MY700JP	MY700JD
Media	Solder paste	SMA and other adhesives
Applicator type	Piezo ejector	Pneumatic valve/Piezo valv
Droplet size	1.9-35nl(3)	5-1,000nl
Min dot diameter	210μm(3)	200μm (this is material dependent)
Nozzle sizes	N/A	50-400μm
Syringe size	30cc	5, 10, 30cc

(3) Please contact a Mycronic representative for specific details.

OPTIONAL FEATURES	MY700JX	
	MY700JP	MY700JD
Hermes communication	•	•
2D inspect and repair—paste present detection	•	
High speed—1,080,000dph	•	
SMD adhesive—jet printing of SMA	•	•
Fine pitch—jet printing for fine pitch components	•	
Shared databases	•	•
PCB ID—board traceability	•	•
Serial start—automatic start	•	•
Dual layout	•	•
Dual heads	•	•
Board indexing	•	•
Cleaning station for ejector	•	
Cleaning station for applicator		•
Internal buffering 200mm	•	•
Internal buffering 250mm	•	•
Extended Internal Conveyor—For boards up to 915 mm in length	•	•
Foot SMEMA—spacer for SMEMA height	•	•
Vacuum clamping	•	•
Fiducial recognition on-the-fly	•	•
Stop pin	•	•
Weigh station	•	•
AI2—active inspection interface, repair loop	•	
E-mapping—external information; “bad board” and “fiducial”	•	•

Available options per product model.

BOARD HANDLING	
Board thickness range ⁽⁴⁾	0.4-6.0 (0.016”-0.24”)
Overboard clearance	35mm (1 3/8”)
Underboard clearance	25mm (1”)
Board edge clearance, top	3mm (1/8”)
Board edge clearance, bottom	4mm (5/32”)
Board warp / bow / twist, max ⁽⁵⁾	± 2mm (± 0.08”)
Board weight, max	5kg (11lbs)
Board transport height	880-930mm (34.6”-36.6”)
Board transport height (SMEMA)	930-975mm (36.6”-38.4”)
Transport direction	R->L, L->R, R->R, L->L, Pass
Lane configuration	Dual lane with optional dual layout

(4) Contact Mycronic sales for thin board applications below 0.4mm.

(5) ±0.4% of PCB diagonal or 2mm, whichever is lowest.

WORK AREA WITH BUFFER SIZE 200mm				
		Indexing	Buffer	Dimensions
		Maximum	Length	No
Yes ⁽⁶⁾	No			400mm
	No			510/915 ⁽⁷⁾ mm
	Width	Single Lane Mode		580mm
		Dual Lane Mode		310mm
Minimum	Length		70mm	
	Width		40/80 ⁽⁸⁾ mm	

(6) Requires Board Indexing option.

(7) Requires Extended Internal Conveyor.

(8) Minimum Width with stop pin.

WORK AREA WITH BUFFER SIZE 250mm				
		Indexing	Buffer	Dimensions
		Maximum	Length	No
Yes ⁽⁶⁾	No			300mm
	No			410mm
	Width	Single Lane Mode		580mm
		Dual Lane Mode		310mm
Minimum	Length		70mm	
	Width		40/80 ⁽⁸⁾ mm	

SOFTWARE
Factory level programming software—Factory Logix Express (PnP interface available)
Advanced Gerber import—MYCenter Analysis
Database server

SOFTWARE
Individual deposit programming—optimizing quality for every solder joint
Quick mode programming—automatch
Handling multi-level boards—editable jetting height
Automatic board stretch and board warpage compensation
Automatic verification of paste type and due date
CAD/Gerber import, all common formats
On-the-spot revisions
No stencils required
Automatic conveyor width adjustment
Closed system for solder paste—clean process
Operator independent quality
Compact footprint
Internal buffering
Good accessibility, front and rear hoods
Online Editor
Bad board exclusion, using mark or fiducial
Program lifecycle management

INSTALLATION

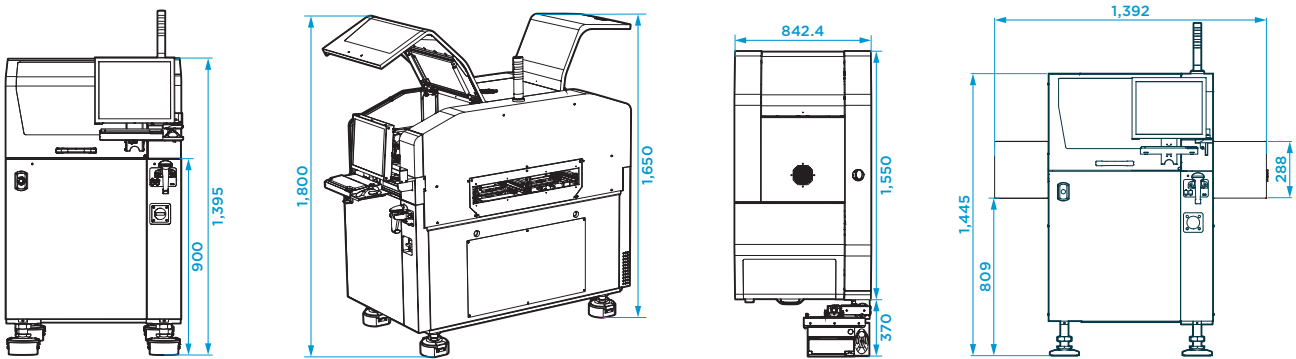
Machine weight	1,600kg (3,530lbs)
System Footprint	843x1,550mm
Power requirements	4kW (peak)
Power consumption	3kVA
Voltage	3 phase AC 200/220/240/380/400/420V ± 10%
Air pressure	5-10bar (70-140PSI) ⁽⁹⁾
Air quality	ISO 8573-1 4 4 4
Air consumption, max	250l/min (9CFM)
Ambient temperature	+18°C to +32°C, 30-80% RH
Clean room	Fulfills class 10,000
Altitude	Lower than 1,000m above sea level
Sound level	68dB(A)

(9) Min recommended 7bar (100PSI) for JD and JX model with applicator HV-2000JD.

DIMENSIONS

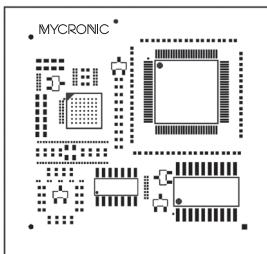
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MY700 JET PRINTER AND JET DISPENSER



REFERENCE BOARD, SOLDER PASTE

Panel of 6 PCBs with a total of 954 components. Reference board throughput includes board transfer, fiducial search, height measurement and jet printing of solder paste.



Component list

O201	65pcs
O402	73pcs
O603	12pcs
BGA49	1pcs
SO14	1pcs
SO20	1pcs
SOT23	5pcs
TQFP100	1pcs

No. of pads 498

Throughput of 49 000 CPH with dual heads in dual lane mode.

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